L Number	Hits	Search Text	DB	Time stamp
2	1	((semiconductor) and (conductive or	USOCR	2004/05/11 09:38
1		conductor or interconnect or interconnection		
		or interconnecting) and dielectric and		İ
[		(ablate or erosion or ablation or erode or		
		eroded or ablated) and (deposit or		]
İ		deposition or deposited)) and laser		
1	17	(semiconductor) and (conductive or conductor	USOCR	2004/05/11 09:42
		or interconnect or interconnection or		
		interconnecting) and dielectric and (ablate		
		or erosion or ablation or erode or eroded or		
		ablated) and (deposit or deposition or		
		deposited)		
3	2098	(semiconductor) and (conductive or conductor	USPAT;	2004/05/11 09:53
		or interconnect or interconnection or	US-PGPUB;	
		interconnecting) and dielectric and (ablate	EPO; JPO;	
		or erosion or ablation or erode or eroded or	DERWENT	
	•	ablated) and (deposit or deposition or		
	100	deposited) and laser and component	HODAM.	2004/05/11 00:52
4	100	(semiconductor) and (conductive or conductor	USPAT;	2004/05/11 09:52
		or interconnect or interconnection or	US-PGPUB; EPO; JPO;	
		interconnecting) and (dielectric near (ablate or erosion or ablation or erode or	DERWENT	
		eroded or ablated)) and (deposit or	DERWENT	
		deposition or deposited) and laser and		
		component		
5	5	(semiconductor) and (conductive or conductor	USPAT;	2004/05/11 09:44
		or interconnect or interconnection or	US-PGPUB;	,,
		interconnecting) and ((dielectric and laser)	EPO; JPO;	1
		near (ablate or erosion or ablation or erode	DERWENT	
		or eroded or ablated)) and (laser near		
		(deposit or deposition or deposited)) and		
		component		ļ
6	5	(semiconductor) and (conductive or conductor	USPAT;	2004/05/11 09:45
		or interconnect or interconnection or	US-PGPUB;	
		interconnecting) and (dielectric near	EPO; JPO;	
		(ablate or erosion or ablation or erode or	DERWENT	
		eroded or ablated)) and (laser near (ablate	1	
		or erosion or ablation or erode or eroded or		,
		ablated)) and (laser near (deposit or		· .
		deposition or deposited)) and component		000110515555
7	31	1 , , , , , , , , , , , , , , , , , , ,	USPAT;	2004/05/11 09:54
		conductor or interconnect or interconnection	US-PGPUB;	
		or interconnecting) and (dielectric near	EPO; JPO;	
	1	(ablate or erosion or ablation or erode or	DERWENT	
		eroded or ablated)) and (deposit or		
		deposition or deposited) and laser and component) and ((component or semiconductor)		
		near (bonding or bond or interconnection or		1
		connect))		
1		COINIECC) /		